

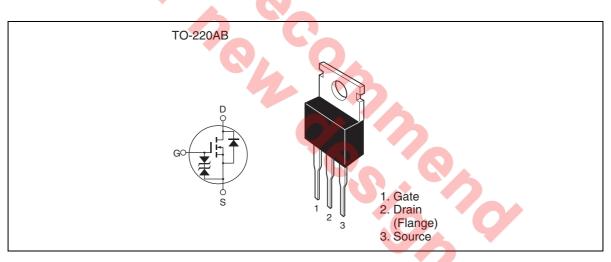
Silicon N Channel MOS FET High Speed Power Switching

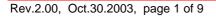
> REJ03G0130-0200Z Rev.2.00 Oct.30.2003

Features

- Low on-resistance $R_{DS(on)} = 8 \text{ m}\Omega \text{ typ.}$
- Low drive current
- Available for 4.5 V gate drive

Outline





Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Ratings	Unit					
Drain to source voltage	V _{DSS}	100	V					
Gate to source voltage	V _{GSS}	±20	V					
Drain current	ID	75	A					
Drain peak current	Note1 I _{D(pulse)}	300	A					
Body-drain diode reverse drain current	I _{DR}	75	A					
Avalanche current	I _{AP} ^{Note3}	50	A					
Avalanche energy	E _{AR} ^{Note3}	166	mJ					
Channel dissipation	Pch ^{Note2}	100	W					
Channel temperature	Tch	150	°C					
Storage temperature	Tstg	-55 to +150	°C					
 Value at Tc = 25°C Value at Tch = 25°C, Rg ≥ 50 Ω 								



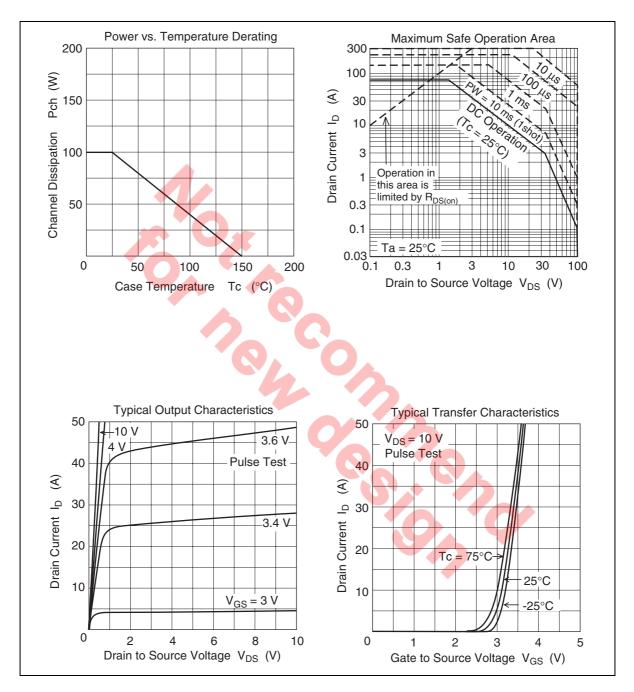
Electrical Characteristics

 $(Ta = 25^{\circ}C)$

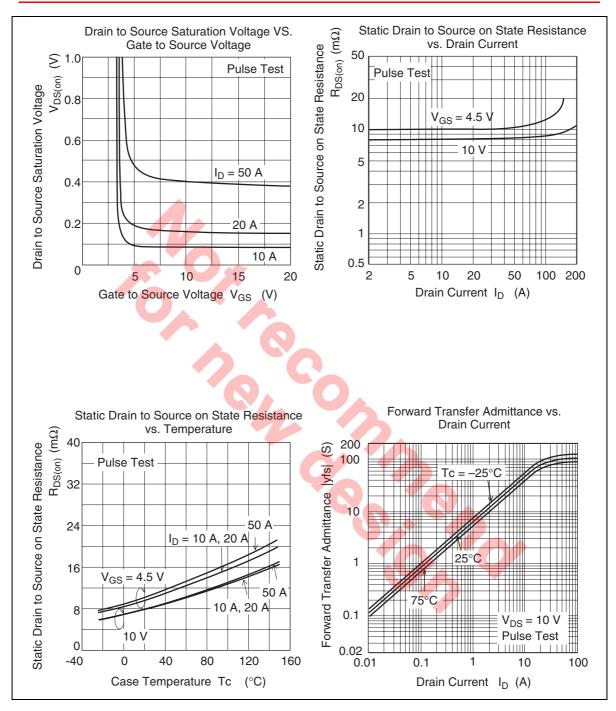
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	100		_	V	$I_{D} = 10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown Voltage	$V_{(BR)GSS}$	±20	_	_	V	$I_G = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source leak current	I _{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 16 V, V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}	_	_	10	μΑ	$V_{DS} = 100 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	$V_{\text{GS(off)}}$	1.5	_	2.5	V	$I_D = 1 \text{ mA}, V_{DS} = 10 \text{ V}^{\text{Note1}}$
Static drain to source on state	R _{DS(on)}	_	8	10	mΩ	$I_D = 37.5 \text{ A}, V_{GS} = 10 \text{ V}^{\text{Note1}}$
resistance		_	10	15	mΩ	$I_D = 37.5 \text{ A}, V_{GS} = 4.5 \text{ V}^{\text{Note1}}$
Forward transfer admittance	y _{fs}	57	95	_	S	$I_D = 37.5 \text{ A}, V_{DS} = 10 \text{ V}^{\text{Note1}}$
Input capacitance	Ciss	_	9700	_	рF	V _{DS} = 10 V
Output capacitance	Coss	_	740	_	рF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	-	330	—	рF	f = 1 MHz
Total gate charge	Qg	2	155	_	nc	V _{DD} = 50 V
Gate to source charge	Qgs	-	35	_	nc	V _{GS} = 10 V
Gate to drain charge	Qgd	_	33	—	nc	I _D = 75 A
Turn-on delay time	t _{d(on)}	—	43	<u> </u>	ns	V_{GS} = 10 V, I_{D} = 37.5 A
Rise time	t _r	7	245	-	ns	$R_L = 0.8 \Omega$
Turn-off delay time	t _{d(off)}		130	-	ns	$R_g = 4.7 \Omega$
Fall time	t _f	-	25		ns	_
Body-drain diode forward voltage	V_{DF}	_	0.93	—	V	I _F = 75 A, V _{GS} = 0
Body–drain diode reverse recovery time	t _{rr}	_	70	5	ns	I _F = 75 A, V _{GS} = 0 diF/ dt = 100 A/μs
Notes: 1. Pulse test					9	0



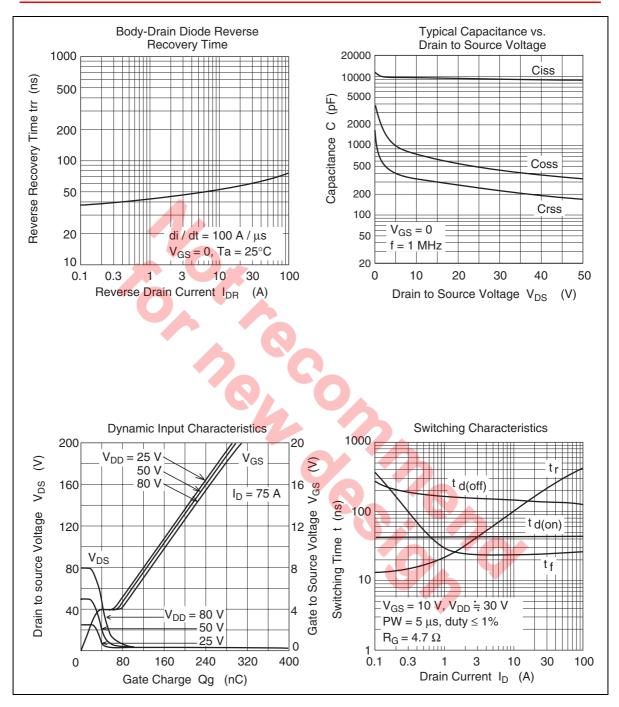
Main Characteristics



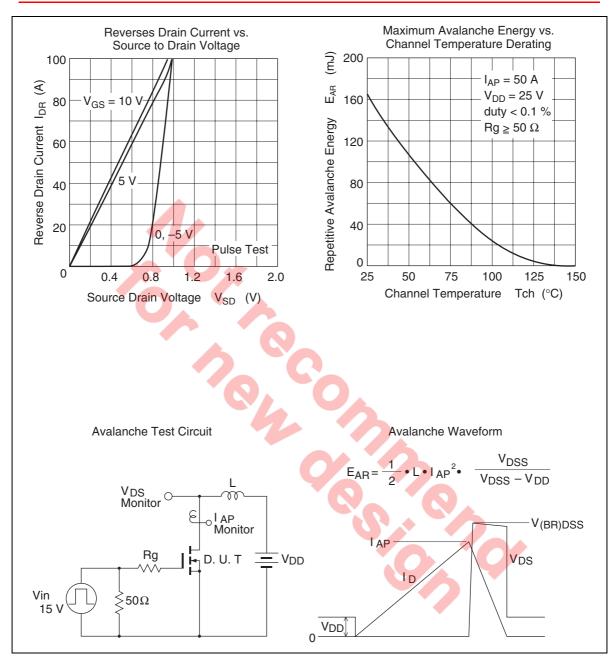




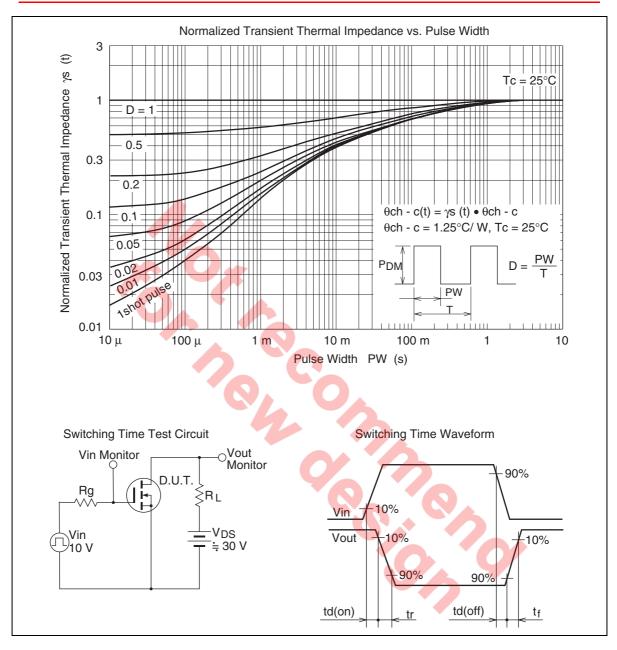






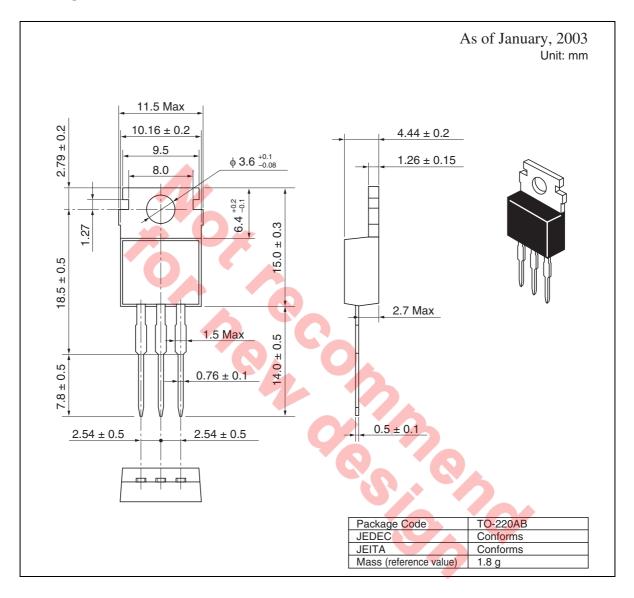








Package Dimensions





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